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## Universal High-Brightness LED Driver

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### Features

- Switch mode controller for single switch LED drivers
- Enhanced drop-in replacement to the HV9910
- Open loop peak current controller
- Internal 8.0 to 450V linear regulator
- Constant frequency or constant off-time operation
- Linear and PWM dimming capability
- Requires few external components for operation

### Applications

- DC/DC or AC/DC LED driver applications
- RGB backlighting LED driver
- Back lighting of flat panel displays
- General purpose constant current source
- Signage and decorative LED lighting
- Chargers

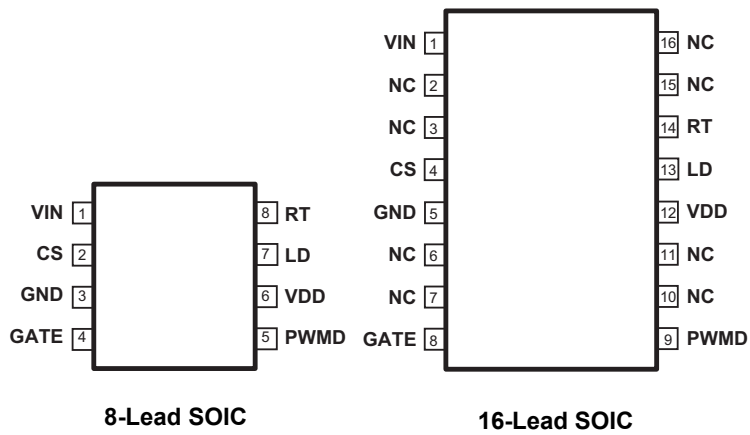
### Description

HV9910B is an open loop, current mode control, LED driver IC. This IC can be programmed to operate in either a constant frequency or constant off-time mode. It includes an 8.0 - 450V linear regulator which allows it to work from a wide range of input voltages without the need for an external low voltage supply. HV9910B includes a PWM-dimming input that can accept an external control signal with a duty ratio of 0 - 100% and a frequency of up to a few kilohertz. It also includes a 0 - 250mV linear dimming input which can be used for linear dimming of the LED current.

HV9910B is ideally suited for buck LED drivers. Since the HV9910B operates in open loop current mode control, the controller achieves good output current regulation without the need for any loop compensation. PWM dimming response is limited only by the rate of rise and fall of the inductor current, enabling very fast rise and fall times. HV9910B requires only three external components, apart from the power stage, to produce a controlled LED current. This makes HV9910B an ideal solution for low cost LED drivers.

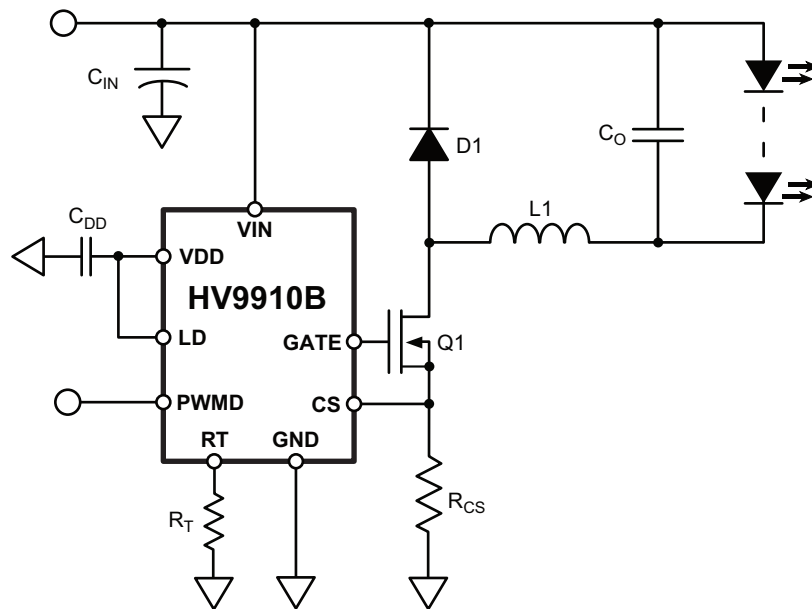
# HV9910B

## Package Type



See [Table 2-1](#) for pin information

## Typical Application Circuit



## 1.0 ELECTRICAL CHARACTERISTICS

### ABSOLUTE MAXIMUM RATINGS

|  |                              |
|--|------------------------------|
| $V_{IN}$ to GND  | -0.5V to +470V               |
| $V_{DD}$ to GND  | 12V                          |
| CS, LD, PWMD, GATE, RT to GND                              | -0.3V to ( $V_{DD} + 0.3V$ ) |
| Operating temperature                                      | -40°C to +125°C              |
| Storage temperature  | -65°C to +150°C              |
| Continuous power dissipation ( $T_A = +25^\circ\text{C}$ ) |                              |
| 8-lead SOIC  | 630 mW                       |
| 16-lead SOIC   | 1300 mW                      |

**Note:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operational listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

### 1.1 ELECTRICAL SPECIFICATIONS

TABLE 1-1: ELECTRICAL CHARACTERISTICS (SHEET 1 OF 2)<sup>1</sup>

| Symbol                    | Parameter  | Note | Min  | Typ | Max  | Units      | Conditions  |
|---------------------------|--|------|------|-----|------|------------|---|
| <b>Input</b>              |  |      |      |     |      |            |   |
| $V_{INDC}$                | Input DC supply voltage range <sup>2</sup>                     | 3    | 8.0  | -   | 450  | V          | DC input voltage  |
| $I_{INSD}$                | Shut-down mode supply current                                  | 3    | -    | 0.5 | 1.0  | mA         | Pin PWMD to GND   |
| <b>Internal Regulator</b> |  |      |      |     |      |            |   |
| $V_{DD}$                  | Internally regulated voltage                                   | -    | 7.25 | 7.5 | 7.75 | V          | $V_{IN} = 8.0V$ , $I_{DD(ext)} = 0$ , 500pF at GATE; $R_T = 226k\Omega$ , PWMD = $V_{DD}$       |
| $\Delta V_{DD, line}$     | Line regulation of $V_{DD}$                                    | -    | 0    | -   | 1.0  | V          | $V_{IN} = 8.0 - 450V$ , $I_{DD(ext)} = 0$ , 500pF at GATE; $R_T = 226k\Omega$ , PWMD = $V_{DD}$ |
| $\Delta V_{DD, load}$     | Load regulation of $V_{DD}$                                    | -    | 0    | -   | 100  | mV         | $I_{DD(ext)} = 0 - 1.0mA$ , 500pF at GATE; $R_T = 226k\Omega$ , PWMD = $V_{DD}$                 |
| UVLO                      | $V_{DD}$ undervoltage lockout threshold                        | 3    | 6.45 | 6.7 | 6.95 | V          | $V_{DD}$ rising   |
| $\Delta UVLO$             | $V_{DD}$ undervoltage lockout hysteresis                       | -    | -    | 500 | -    | mV         | $V_{DD}$ falling  |
| $I_{IN,MAX}$              | Current that the regulator can supply before IC goes into UVLO | 4    | 5.0  | -   | -    | mA         | $V_{IN} = 8.0V$   |
| <b>PWM Dimming</b>        |  |      |      |     |      |            |   |
| $V_{EN(lo)}$              | Pin PWMD input low voltage                                     | 3    | -    | -   | 0.8  | V          | $V_{IN} = 8.0 - 450V$   |
| $V_{EN(hi)}$              | Pin PWMD input high voltage                                    | 3    | 2.0  | -   | -    | V          | $V_{IN} = 8.0 - 450V$   |
| $R_{EN}$                  | Pin PWMD pull-down resistance at PWMD                          | -    | 50   | 100 | 150  | k $\Omega$ | $V_{PWMD} = 5.0V$   |

# HV9910B

**TABLE 1-1: ELECTRICAL CHARACTERISTICS (CONTINUED) (SHEET 2 OF 2)<sup>1</sup>**

| Symbol                          | Parameter                               | Note | Min | Typ | Max | Units | Conditions  |
|---------------------------------|---|------|-----|-----|-----|-------|---|
| <b>Current Sense Comparator</b> |   |      |     |     |     |       |   |
| $V_{CS,TH}$                     | Current sense pull-in threshold voltage | -    | 225 | 250 | 275 | mV    | $-40^{\circ}\text{C} < T_A < +85^{\circ}\text{C}$   |
|                                 |   |      | 213 | 250 | 287 |       | $T_A < +125^{\circ}\text{C}$  |
| $V_{OFFSET}$                    | Offset voltage for LD comparator        | 3    | -12 | -   | 12  | mV    |   |
| $T_{BLANK}$                     | Current sense blanking interval         | -    | 150 | 215 | 280 | ns    | $0 < T_A < +85^{\circ}\text{C}$ , $V_{LD} = V_{DD}$ , $V_{CS} = V_{CS,TH} + 50\text{mV}$ after $T_{BLANK}$    |
|                                 |   | -    | 145 | 215 | 315 |       | $-40 < T_A < +125^{\circ}\text{C}$ , $V_{LD} = V_{DD}$ , $V_{CS} = V_{CS,TH} + 50\text{mV}$ after $T_{BLANK}$ |
| $t_{DELAY}$                     | Delay to output                         | -    | -   | 80  | 150 | ns    | $V_{LD} = V_{DD}$ , $V_{CS} = V_{CS,TH} + 50\text{mV}$ after $T_{BLANK}$                                      |
| <b>Oscillator</b>               |   |      |     |     |     |       |   |
| $f_{OSC}$                       | Oscillator frequency                    | -    | 20  | 25  | 30  | kHz   | $R_T = 1.00\text{M}\Omega$  |
|                                 |   | -    | 80  | 100 | 120 |       | $R_T = 226\text{k}\Omega$   |
| <b>Gate Driver</b>              |   |      |     |     |     |       |   |
| $I_{SOURCE}$                    | GATE sourcing current                   | -    | 165 | -   | -   | mA    | $V_{GATE} = 0\text{V}$ , $V_{DD} = 7.5\text{V}$   |
| $I_{SINK}$                      | GATE sinking current                    | -    | 165 | -   | -   | mA    | $V_{GATE} = V_{DD}$ , $V_{DD} = 7.5\text{V}$  |
| $t_{RISE}$                      | GATE output rise time                   | -    | -   | 30  | 50  | ns    | $C_{GATE} = 500\text{pF}$ , $V_{DD} = 7.5\text{V}$  |
| $t_{FALL}$                      | GATE output fall time                   | -    | -   | 30  | 50  | ns    | $C_{GATE} = 500\text{pF}$ , $V_{DD} = 7.5\text{V}$  |

- 1 Specifications are  $T_A = 25^{\circ}\text{C}$ ,  $V_{IN} = 15\text{V}$  unless otherwise noted.
- 2 Also limited by package-power dissipation limit; Whichever is lower.
- 3 Applies over the full operating ambient temperature range of  $-40^{\circ}\text{C} < T_A < +125^{\circ}\text{C}$ .
- 4 For design guidance only

**TABLE 1-2: THERMAL RESISTANCE**

| Package      | $\theta_{ja}$ |
|--------------|---------------|
| 8-Lead SOIC  | 101°C/W       |
| 16-Lead SOIC | 83°C/W        |

## 2.0 PIN DESCRIPTION

The locations of the pins are listed in [Package Type](#).

**TABLE 2-1: PIN DESCRIPTION**

| Pin #       |                            | Function | Description   |
|-------------|----------------------------|----------|---|
| 8-Lead SOIC | 16-Lead SOIC               |          |   |
| 1           | 1                          | VIN      | Input of an 8.0 - 450V linear regulator.  |
| 2           | 4                          | CS       | Current sense pin used to sense the FET current by means of an external sense resistor. When this pin exceeds the lower of either the internal 250mV or the voltage at the LD pin, the GATE output goes low.                    |
| 3           | 5                          | GND      | Ground return for all internal circuitry. This pin must be electrically connected to the ground of the power train.   |
| 4           | 8                          | GATE     | Output GATE driver for an external N-channel power MOSFET.  |
| 5           | 9                          | PWMD     | PWM dimming input of the IC. When this pin is pulled to GND, the GATE driver is turned off. When the pin is pulled high, the GATE driver operates normally.   |
| 6           | 12                         | VDD      | Power supply for all internal circuits. It must be bypassed with a low ESR capacitor to GND ( $\geq 0.1\mu\text{F}$ ).  |
| 7           | 13                         | LD       | Linear dimming input and sets the current sense threshold as long as the voltage at the pin is less than 250mV (typ).   |
| 8           | 14                         | RT       | Sets the oscillator frequency. When a resistor is connected between RT and GND, the HV9910B operates in constant frequency mode. When the resistor is connected between RT and GATE, the IC operates in constant off-time mode. |
| -           | 2, 3, 6, 7, 10, 11, 15, 16 | NC       | No connection   |

# HV9910B

## 3.0 APPLICATION INFORMATION

HV9910B is optimized to drive buck LED drivers using open-loop, peak current mode control. This method of control enables fairly accurate LED current control without the need for high side current sensing or the design of any closed loop controllers. The IC uses very few external components and enables both Linear and PWM-dimming of the LED current.

A resistor connected to the RT pin programs the frequency of operation (or the off-time). The oscillator produces pulses at regular intervals. These pulses set the SR flip-flop in the HV9910B which causes the GATE driver to turn on. The same pulses also start the blanking timer, which inhibits the reset input of the SR flip-flop and prevent false turn-offs due to the turn-on spike. When the FET turns on, the current through the inductor starts ramping up. This current flows through the external sense resistor  $R_{CS}$  and produces a ramp voltage at the CS pin. The comparators are constantly comparing the CS pin voltage to both the voltage at the LD pin and the internal 250mV. Once the blanking timer is complete, the output of these comparators is allowed to reset the flip-flop. When the output of either one of the two comparators goes high, the flip flop is reset and the GATE output goes low. The GATE goes low until the SR flip-flop is set by the oscillator. Assuming a 30% ripple in the inductor, the current sense resistor  $R_{CS}$  can be set using:

$$R_{CS} = \frac{0.25V(\text{or } V_{LD})}{1.15 \cdot I_{LED}(A)}$$

Constant frequency peak current mode control has an inherent disadvantage – at duty cycles greater than 0.5, the control scheme goes into subharmonic oscillations. To prevent this, an artificial slope is typically added to the current sense waveform. This slope compensation scheme will affect the accuracy of the LED current in the present form. However, a constant off-time peak current control scheme does not have this problem and can easily operate at duty cycles greater than 0.5. This control scheme also gives inherent input voltage rejection, making the LED current almost insensitive to input voltage variations. However, this scheme leads to variable frequency operation and the frequency range depends greatly on the input and output voltage variation. HV9910B makes it easy to switch between the two modes of operation by changing one connection (see [Section 3.3 “Oscillator”](#)).

### 3.1 Input Voltage Regulator

HV9910B can be powered directly from its VIN pin and can work from 8.0 - 450VDC at its VIN pin. When a voltage is applied at the VIN pin, the HV9910B maintains a constant 7.5V at the VDD pin. This voltage is used to power the IC and any external resistor dividers needed

to control the IC. The VDD pin must be bypassed by a low-ESR capacitor to provide a low impedance path for the high frequency current of the output GATE driver.

HV9910B can also be operated by supplying a voltage at the VDD pin greater than the internally regulated voltage. This will turn off the internal linear regulator of the IC and the HV9910B will operate directly off the voltage supplied at the VDD pin. Please note that this external voltage at the VDD pin should not exceed 12V.

Although the VIN pin of the HV9910B is rated up to 450V, the actual maximum voltage that can be applied is limited by the power dissipation in the IC. For example, if an 8-pin SOIC (junction to ambient thermal resistance  $R_{\theta j-a} = 128^{\circ}\text{C}/\text{W}$ ) HV9910B draws about  $I_{IN} = 2.0\text{mA}$  from the VIN pin, and has a maximum allowable temperature rise of the junction temperature limited to about  $\Delta T = 100^{\circ}\text{C}$ , the maximum voltage at the VIN pin would be:

$$V_{IN(\text{MAX})} = \frac{\Delta T}{R_{\theta j-a}} \cdot \frac{1}{I_{IN}} = \frac{100^{\circ}\text{C}}{128^{\circ}\text{C}/\text{W}} \cdot \frac{1}{2\text{mA}} = 390\text{V}$$

In these cases, to operate the HV9910B from higher input voltages, a Zener diode can be added in series with the VIN pin to divert some of the power loss from the HV9910B to the Zener diode. In the above example, using a 100V Zener diode will allow the circuit to easily work up to 450V.

The input current drawn from the VIN pin is a sum of the 1.0mA current drawn by the internal circuit and the current drawn by the GATE driver. The GATE driver depends on the switching frequency and the GATE charge of the external FET).

$$I_{IN} \approx 1.0\text{mA} + Q_g \cdot f_s$$

In the above equation,  $f_s$  is the switching frequency and  $Q_g$  is the GATE charge of the external FET (which can be obtained from the data sheet of the FET).

### 3.2 Current Sense

The current sense input of the HV9910B goes to the non-inverting inputs of two comparators. The inverting terminal of one comparator is tied to an internal 250mV reference, whereas the inverting terminal of the other comparator is connected to the LD pin. The outputs of both these comparators are fed into an OR GATE and the output of the OR GATE is fed into the reset pin of the flip-flop. Thus, the comparator which has the lowest voltage at the inverting terminal determines when the GATE output is turned off.

The outputs of the comparators also include a 150-280ns blanking time which prevents spurious turn-offs of the external FET due to the turn-on spike normally present in peak current mode control. In rare cases, this internal blanking might not be enough to filter out the turn-on spike. In these cases, an external RC filter needs to be added between the external sense resistor (RCS) and the CS pin.

Please note that the comparators are fast with a typical 80ns response time. Hence these comparators are more susceptible to be triggered by noise than the comparators of the HV9910. A proper layout minimizing external inductances will prevent false triggering of these comparators.

### 3.3 Oscillator

The oscillator in the HV9910B is controlled by a single resistor connected at the RT pin. The equation governing the oscillator time period  $t_{OSC}$  is given by:

$$t_{OSC}(\mu s) = \frac{R_T(k\Omega) + 22}{25}$$

If the resistor is connected between RT and GND, HV9910B operates in a constant frequency mode and the above equation determines the time-period. If the resistor is connected between RT and GATE, the HV9910B operates in a constant off-time mode and the above equation determines the off-time.

### 3.4 Gate Output

The GATE output of the HV9910B is used to drive an external FET. It is recommended that the GATE charge of the external FET be less than 25nC for switching frequencies  $\leq 100$ kHz and less than 15nC for switching frequencies  $> 100$ kHz.

### 3.5 Linear Dimming

The Linear Dimming pin is used to control the LED current. There are two cases when it may be necessary to use the Linear Dimming pin.

1. In some cases, when using the internal 250mV, it may not be possible to find the exact RCS value required to obtain the LED current. In these cases, an external voltage divider from the VDD pin can be connected to the LD pin to obtain a voltage (less than 250mV) corresponding to the desired voltage across  $R_{CS}$ .
2. Linear dimming may be desired to adjust the current level to reduce the intensity of the LEDs. In these cases, an external 0-250mV voltage can be connected to the LD pin to adjust the LED current during operation.

To use the internal 250mV, the LD pin can be connected to VDD.

**Note:** Although the LD pin can be pulled to GND, the output current will not go to zero. This is due to the presence of a minimum on-time, which is equal to the sum of the blanking time and the delay to output time, or about 450ns. This minimum on-time causes the FET to be on for a minimum of 450ns, and thus the LED current when LD = GND is not zero. This current is also dependent on the input voltage, inductance value, forward voltage of the LEDs, and circuit parasitics. To get zero LED current, the PWMD pin has to be used.

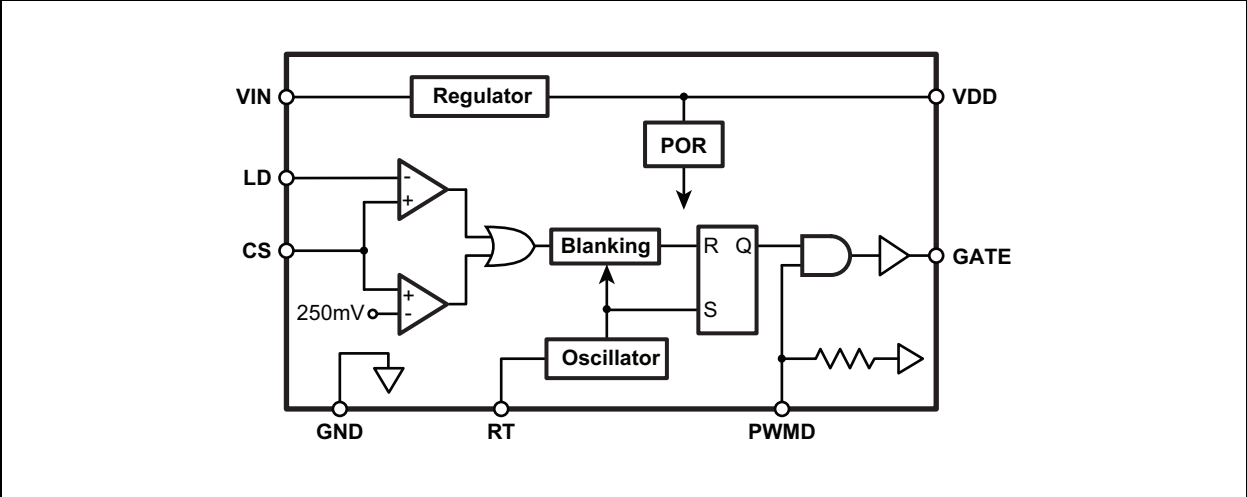
### 3.6 PWM Dimming

PWM Dimming can be achieved by driving the PWMD pin with a low frequency square wave signal. When the PWM signal is zero, the GATE driver is turned off; when the PWMD signal is high, the GATE driver is enabled. The PWMD signal does not turn off the other parts of the IC, therefore, the response of the HV9910B to the PWMD signal is almost instantaneous. The rate of rise and fall of the LED current is thus determined solely by the rise and fall times of the inductor current.

To disable PWM dimming and enable the HV9910B permanently, connect the PWMD pin to VDD.

# HV9910B

FIGURE 3-1: INTERNAL BLOCK DIAGRAM

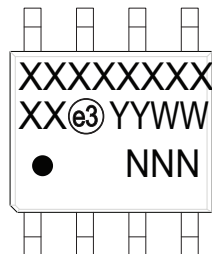




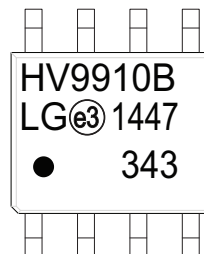
## 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

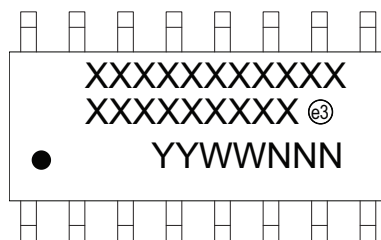
8-lead SOIC



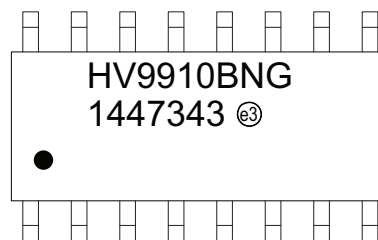
Example



16-lead SOIC



Example

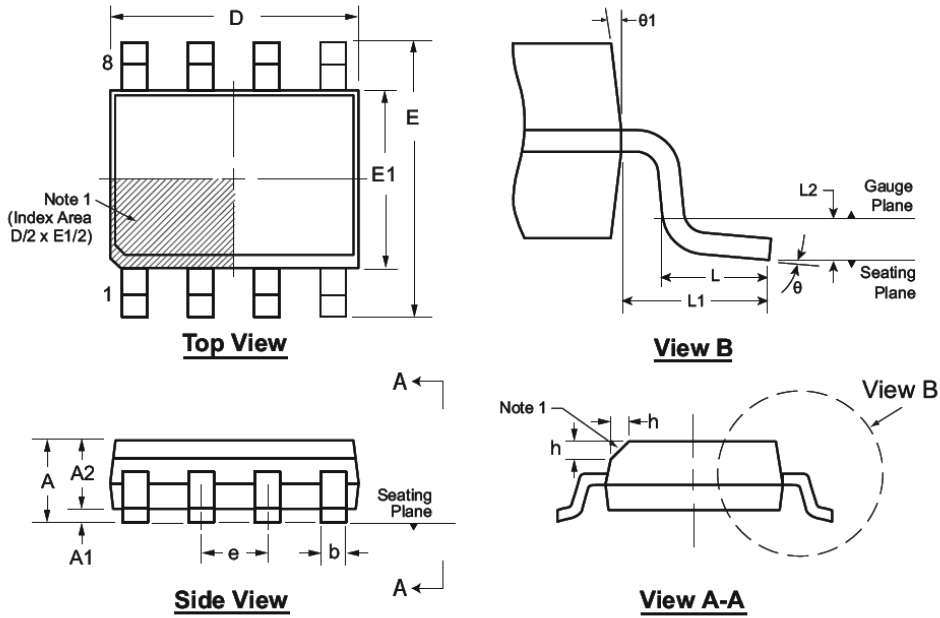


|                |                 |   |
|----------------|-----------------|---|
| <b>Legend:</b> | XX...X          | Product Code or Customer-specific information   |
|                | Y               | Year code (last digit of calendar year)   |
|                | YY              | Year code (last 2 digits of calendar year)  |
|                | WW              | Week code (week of January 1 is week '01')  |
|                | NNN             | Alphanumeric traceability code  |
|                | <sup>(e3)</sup> | Pb-free JEDEC <sup>®</sup> designator for Matte Tin (Sn)  |
|                | *               | This package is Pb-free. The Pb-free JEDEC designator ( <sup>(e3)</sup> ) can be found on the outer packaging for this package. |

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

# HV9910B

## 8-Lead SOIC (Narrow Body) Package Outline (LG/TG) 4.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at [www.microchip.com/packaging](http://www.microchip.com/packaging).

**Note:**

1. This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

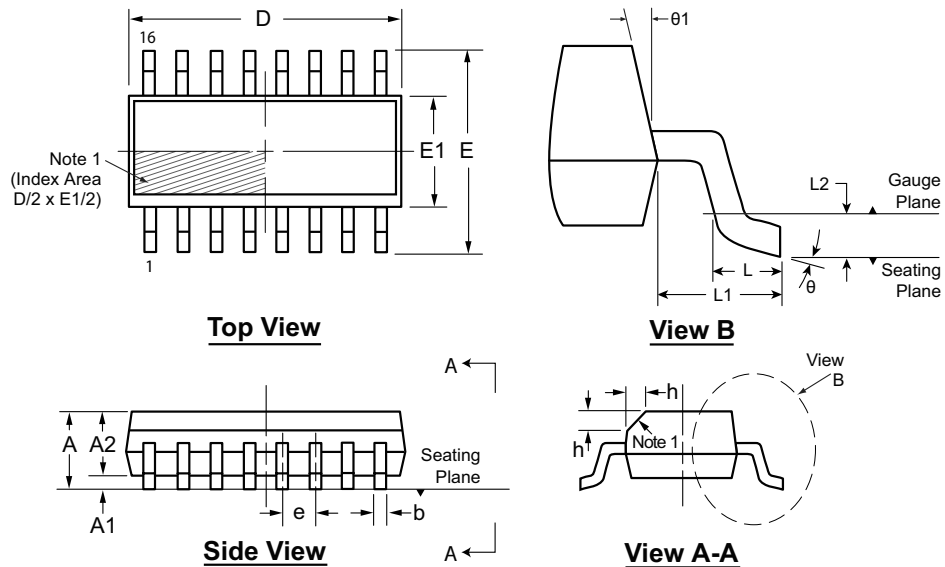
| Symbol         | A   | A1    | A2   | b     | D    | E     | E1    | e     | h        | L    | L1   | L2       | θ        | θ1 |     |
|----------------|-----|-------|------|-------|------|-------|-------|-------|----------|------|------|----------|----------|----|-----|
| Dimension (mm) | MIN | 1.35* | 0.10 | 1.25  | 0.31 | 4.80* | 5.80* | 3.80* | 1.27 BSC | 0.25 | 0.40 | 1.04 REF | 0.25 BSC | 0° | 5°  |
|                | NOM | -     | -    | -     | -    | 4.90  | 6.00  | 3.90  |          | -    | -    |          | -        | -  |     |
|                | MAX | 1.75  | 0.25 | 1.65* | 0.51 | 5.00* | 6.20* | 4.00* |          | 0.50 | 1.27 |          | -        | 8° | 15° |

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.

\* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

## 16-Lead SOIC (Narrow Body) Package Outline (NG) 9.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at [www.microchip.com/packageing](http://www.microchip.com/packageing).

**Note:**

1. This chamfer feature is optional. If it is not present, then a Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

| Symbol         | A   | A1    | A2   | b     | D    | E      | E1    | e     | h           | L    | L1   | L2          | $\theta$ | $\theta_1$ |     |    |   |
|----------------|-----|-------|------|-------|------|--------|-------|-------|-------------|------|------|-------------|----------|------------|-----|----|---|
| Dimension (mm) | MIN | 1.35* | 0.10 | 1.25  | 0.31 | 9.80*  | 5.80* | 3.80* | 1.27<br>BSC | 0.25 | 0.40 | 1.04<br>REF | 0.25     | BSC        | 0°  | 5° |   |
|                | NOM | -     | -    | -     | -    | 9.90   | 6.00  | 3.90  |             | -    | -    |             | -        |            | -   | -  | - |
|                | MAX | 1.75  | 0.25 | 1.65* | 0.51 | 10.00* | 6.20* | 4.00* |             | 0.50 | 1.27 |             | 8°       |            | 15° |    |   |

JEDEC Registration MS-012, Variation AC, Issue E, Sept. 2005.

\* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

# HV9910B

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## APPENDIX A: REVISION HISTORY

### Revision A (January 2015)

- Update file to new format

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| <u>PART NO.</u> | <u>XX</u>  | - | <u>X</u>   | - | <u>X</u>   |
|-----------------|--|---|--|---|------------|
| Device          | Package Options  |   | Environmental                                    |   | Media Type |
| Device:         | HV9910B= Universal High-Brightness LED Driver  |   |  |   |            |
| Package:        | LG   | = | 8-lead SOIC                                      |   |            |
|                 | NG   | = | 16-lead SOIC                                     |   |            |
| Environmental   | G  | = | Lead (Pb)-free/ROHS-compliant package            |   |            |
| Media Type:     | (blank)  | = | 3300/reel for LG package, 45/Tube for NG package |   |            |
|                 | M901   | = | 2600/reel for NG package                         |   |            |
|                 | M934   | = | 2600/reel for NG package                         |   |            |
| <b>Note:</b>    | For Media Types M901 and M934, the base quantity for tape and reel was standardized to 2600/reel. Both options will result in delivery of the same number of parts/reel. |   |  |   |            |

### Examples:

- a) HV9910BLG-G: 8-lead SOIC package, 3300/reel.
- b) HV9910BNG-G: 16-lead SOIC package, 45/tube
- c) HV9910BNG-G-M901: 16-lead SOIC package, 2600/reel.
- d) HV9910BNG-G-M934: 16-lead SOIC package, 2600/reel.

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**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
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